

STS RIE SYSTEM

GASES USED: CF₄, SF₆, CHF₃, O₂

RF POWER RANGE: 10W to 600W

CHAMBER PRESSURE RANGE: 10mTorr to 500mTorr

MATERIALS ALLOWED: Silicon, Poly-Si, SiO₂, Si₃N₄, n/p-PR, Metal**

TRAINING PROCESS:

- Get approval from your Guide/Faculty Advisor
- Contact the System Owner
- You need to attend at least four etch sessions with any authorized user
- After that you need to attend one or two hands-on session
- A test will be taken after that and authorization will be given if cleared, else you need to go for few more training sessions before next test

**** Metals will be allowed inside the chamber only in certain conditions like metal is not going to be exposed to the plasma or after discussion with concerned faculties.**

SYSTEM OWNER		
Sandeep S. S.	sandeep.gec@gmail.com	9619527371
AUTHORIZED USERS		
Sudhanshu Shukla	sudhanshu@ee.iitb.ac.in	
Naveenkumar N.V	naveenkumar.nv@gmail.com	9167563949
Prasenjit Ray	pray@ee.iitb.ac.in	9757399482